

Product Data Sheet

Wafer Flux WS-3401-A

Features

- Water-soluble
- Viscosity suitable for 150–300 mm wafers as a damming flux
- No residue after multiple reflow/cleaning cycles
- Uniform bump shape
- Halogen-free
- Suitable for SnPb and Pb-free, and high temperature applications
- Non-corrosive to underbump metallization

Introduction

Wafer Flux WS-3401-A is a high viscosity semiconductor-grade flux, specifically optimized as a damming flux for the edge of the wafer and to prevent backside contamination. Working with the natural surface tension of solder **WS-3401-A** produces uniform hemispherical bumps without solder-robbing or solder-bridging.

Properties

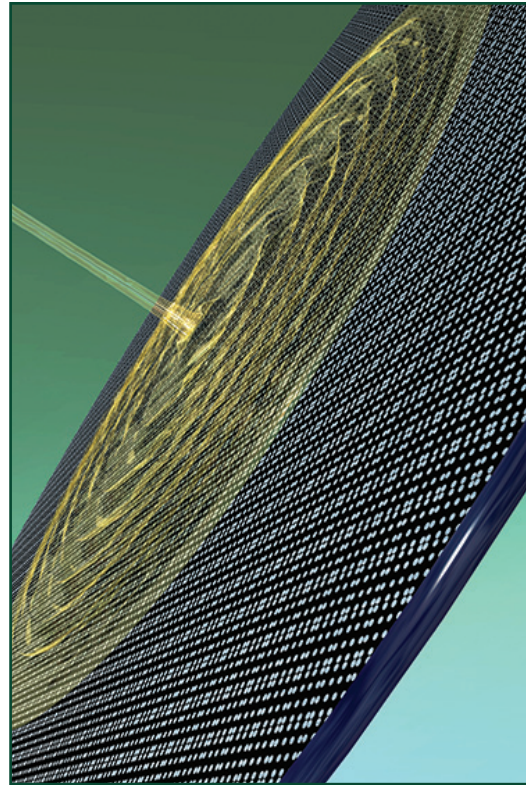
Property	Value	Test Method
Flux Type Classification:	M0	J-STD-004 (IPC-TM-650: 2.3.32 and 2.3.33)
Typical Viscosity:	1.5Kcps (peak)	Brookfield HB DVII +CP
SIR (Ohms, post cleaning):	Pass (>10 ⁹ after 7days @85°C and 85% RH)	J-STD-004 (IPC-TM-650: 2.6.33 IPC-B-24)
Typical Acid Value:	81mg KOH/g	Titration
Specific Gravity:	1.08g/cc	J-STD-004B
Color:	Deep Amber to Light Brown	Visual
Shelf Life:	6 months	0°C to +25°C

All information is for reference only. Not to be used as incoming product specifications.

Application

WS-3401-A can be applied by standard spin-coating techniques, but may be too viscous for many applications.

For copper pillar applications, **WS-3401-A** is used (in conjunction with **WS-3401**) as a damming flux around the edge of the wafer, to prevent backside contamination.



Cleaning

WS-3401-A is designed to be cleaned with DI water or water with an added cleaner. Ideal conditions for spray cleaning are 25°C or higher for >1 minute at >60psi.

Packaging

Wafer Flux WS-3401-A is available in containers from 100g to 3.2kg (1 gallon). Other packaging can be provided to meet specific requirements.

Storage

WS-3401-A containers should be stored at 0°C to 25°C for maximum shelf life. Storage temperatures should not exceed 25°C for more than 4 days, and should never exceed 30°C. After removing from cold storage, **WS-3401-A** should be allowed to stand for at least 4 hours at room temperature before using.

OVER→

Form No. 98764 R1

www.indium.com

askus@indium.com

ASIA: Singapore, Cheongju: +65 6268 8678
 CHINA: Suzhou, Shenzhen, Liuzhou: +86 (0)512 628 34900
 EUROPE: Milton Keynes, Torino: +44 (0) 1908 580400
 USA: Utica, Clinton, Chicago: +1 315 853 4900



©2012 Indium Corporation

ISO 9001
REGISTERED

Wafer Flux WS-3401-A

Technical Support

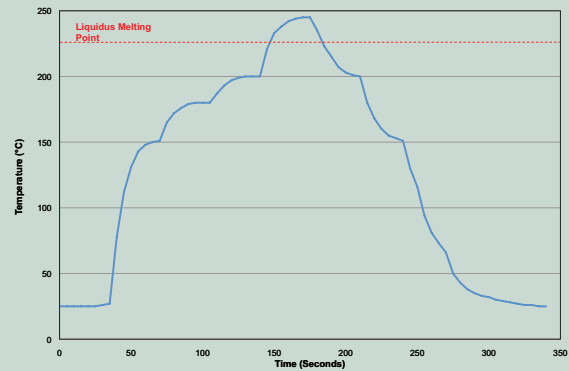
Indium Corporation sets the industry standard in providing rapid response, on-site technical support for our customers worldwide. Indium Corporation's team of Technical Support Engineers can provide expertise in all aspects of materials science and semiconductor packaging process applications.

Material Safety Data Sheets

The MSDS for this product can be found online at: <http://www.indium.com/msds>

Reflow

Recommended Profile:



The above profile is recommended as a starting point for 300mm wafers with SnAg solder microbumps, and should be optimized by the user to meet their individual process needs. Wafers should be reflowed in a nitrogen atmosphere (<10ppm O₂ is recommended, but <20ppm O₂ may be feasible; however, results may not be optimal). Note that bridging or solder thieving may be seen for fine pitch microbumps (<60microns) on copper pillars, and that reducing the peak temperature will reduce the occurrence of this failure mode.

This product data sheet is provided for general information only. It is not intended, and shall not be construed, to warrant or guarantee the performance

of the products described which are sold subject exclusively to written warranties and limitations thereon included in product packaging and invoices.

www.indium.com

askus@indium.com

ASIA: Singapore, Cheongju: +65 6268 8678
 CHINA: Suzhou, Shenzhen, Liuzhou: +86 (0)512 628 34900
 EUROPE: Milton Keynes, Torino: +44 (0) 1908 580400
 USA: Utica, Clinton, Chicago: +1 315 853 4900



©2012 Indium Corporation

ISO 9001
REGISTERED